



Material Composition Declaration

EPC2308

Company Name	Efficient Power Conversion (EPC)	Issue Date:	11/1/2024
Contact Name:	Yanping Ma	Contact Title:	VP Quality
Contact Phone:	(310) 615-0280	Contact Email:	yanping.ma@epc-co.com
Part Weight:	30.3 mg	Type of Product:	eGaN FET in FCQFN package

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	4.9520	16.3507	17.2275	163507
	Silicon oxide	7631-86-9	0.0387	0.1278		1278
	Silicon nitride	12033-89-5	0.0208	0.0686		686
	Gallium nitride	25617-97-4	0.0421	0.1391		1391
	Aluminum	7429-90-5	0.0648	0.2139		2139
	Aluminum nitride	24304-00-5	0.0089	0.0295		295
	Titanium	7440-32-6	0.0023	0.0074		74
	Titanium nitride	25583-20-4	0.0130	0.0430		430
	Copper	7440-50-8	0.0011	0.0036		36
	Tungsten	7440-33-7	0.0053	0.0175		175
	Polyimide		0.0686	0.2265		2265
Under Bump Metal	Titanium	7440-32-6	0.0005	0.0016	0.0176	16
	Copper	7440-50-8	0.0048	0.0159		159
Solder Bump	Copper	7440-50-8	0.4057	1.3397	1.8305	13397
	Nickel	7440-02-0	0.0288	0.0951		951
	Tin	7440-31-5	0.1177	0.3886		3886
	Silver	7440-22-4	0.0022	0.0071		71
Package	Copper	7440-50-8	11.7262	38.7184	80.9243	387184
	Iron	7439-89-6	0.3007	0.9928		9928
	Mold Compound		11.7959	38.9484		389484
	Tin	7440-31-5	0.6859	2.2648		22648
Sum in total:			30.2859	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.